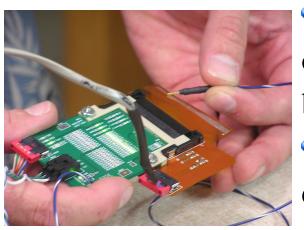




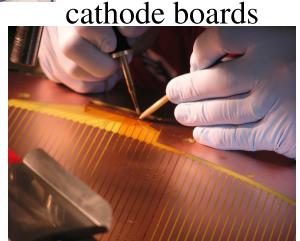
Rigid-flex assemblies



•Purpose is to connect the traces on the cathode boards to the readout daughter boards

•The rigid-flex assemblies have been tested electrically and soldered and glued onto all







Experience has motivated some small design changes for final version...

→Increase the pitch between traces to make soldering more reliable



Assembling the Full-scale Prototype







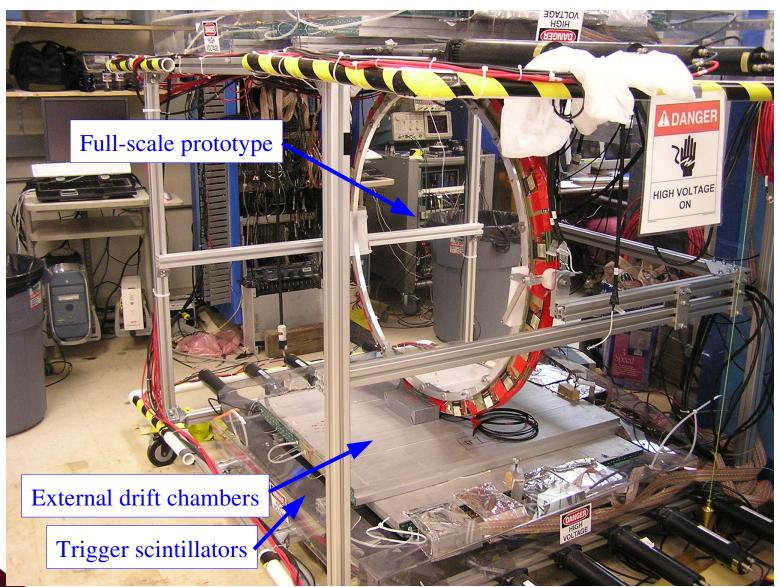


Three-layer Full-Scale Prototype





Full-Scale Prototype in Test Stand

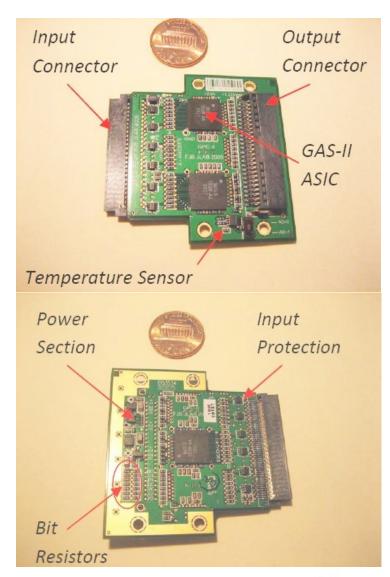


GAS-II/GPC-II Preamplifier

- •Version 2 of ASIC = GAS-II
 - Two gain settings:
 - •~0.7 mV/fC (FDC anodes, CDC wires)
 - •~3.0 mV/fC (FDC cathodes)
 - Discriminator for FDC anode wires



- •Analog output for FDC cathodes and CDC wires
 - New version of daughter board(GPC-II), compatible with new chip

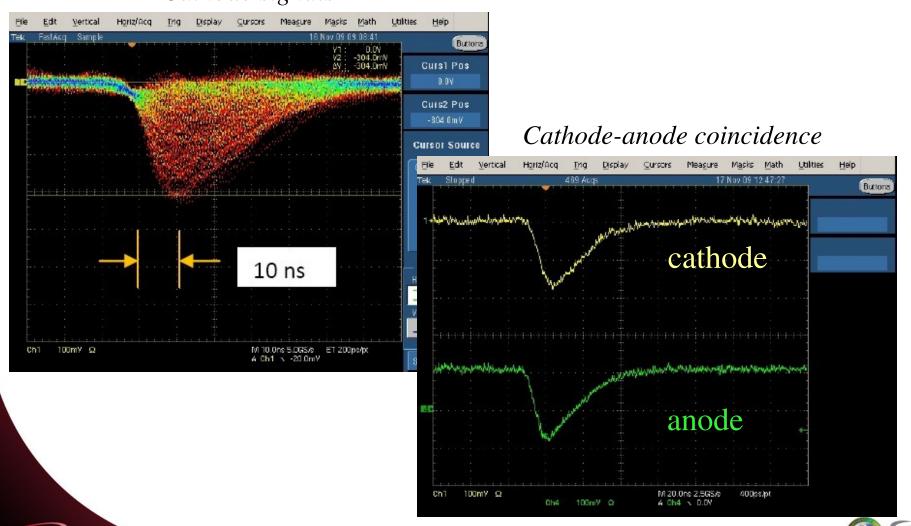




First Signals from Full-Scale Prototype

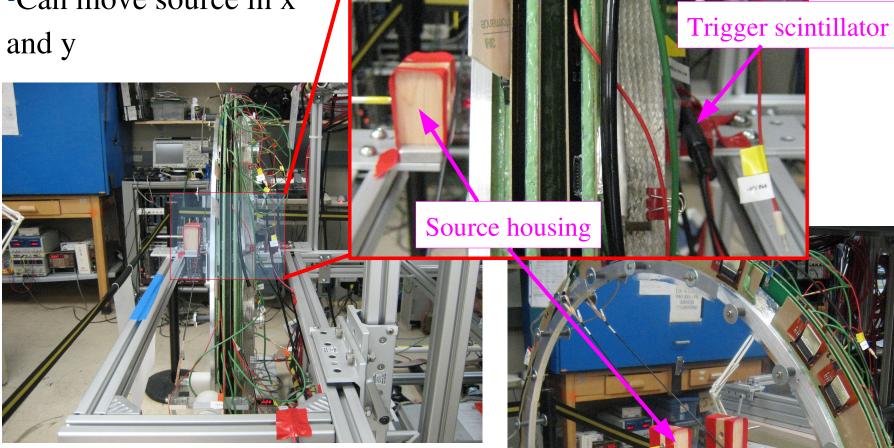
Cathode signals

Jefferson Lab



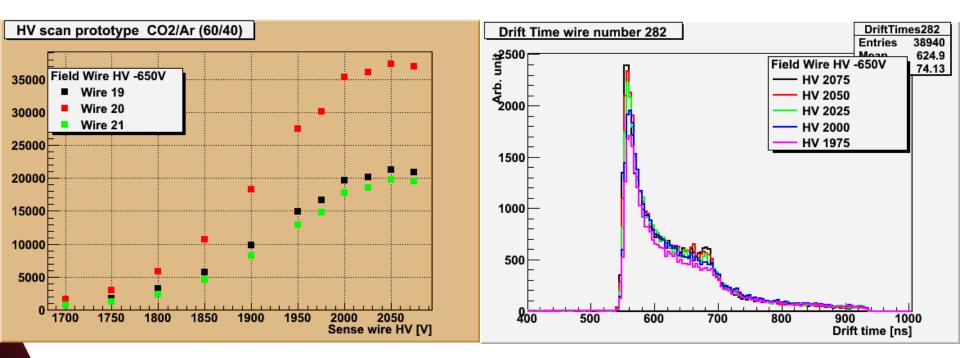
Tests of 2-layer prototype with sources

•Can move source in x



Plateau curves and drift time distributions

Sr-90 source





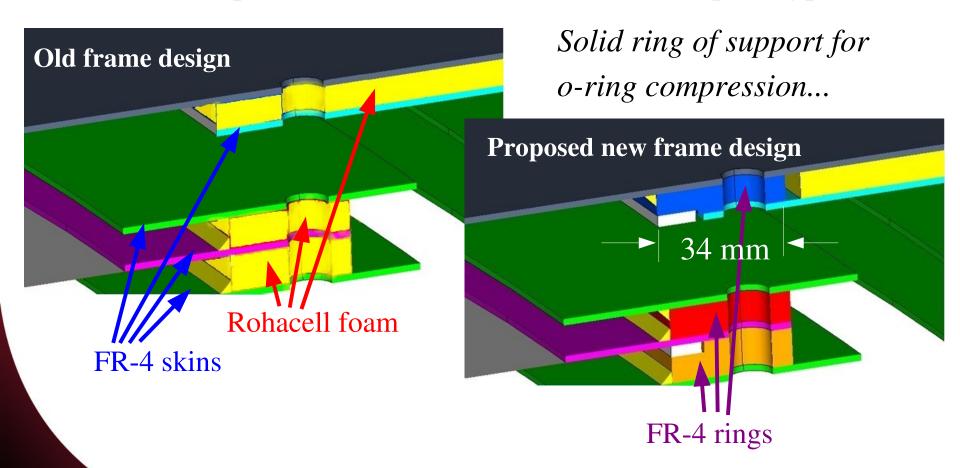
Gas-sealing issues with current design

- •We have been experiencing difficulties making sure that the prototype is gas-tight
- •Problem areas have been identified:
 - •Light-weight foam core crushed by over-torquing screws
 - •Flaws in wire-board design leading to improper sealing surface for o-rings
 - Uneven surface and unfilled vias on front side
 - Bad placement of capacitors on back side
 - •Flaws will addressed in next (production) revision of boards



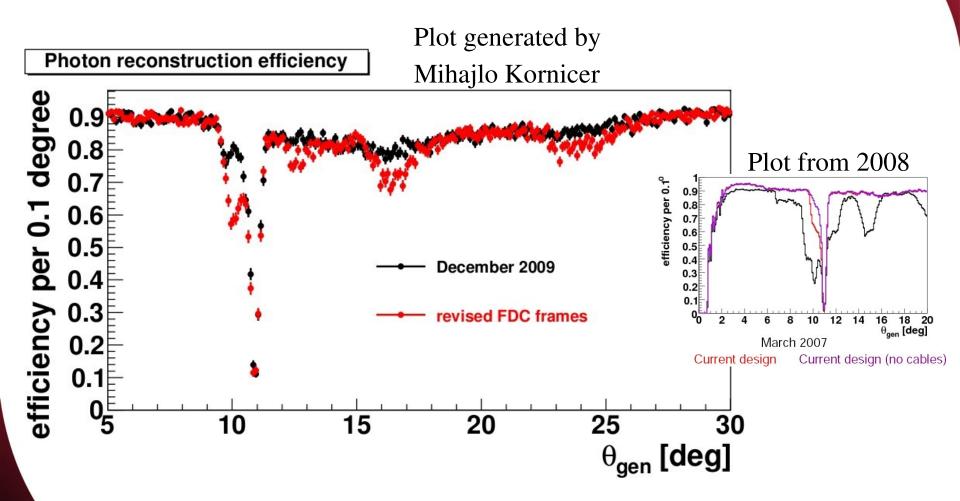
Modified Frame Design

•Problems with sealing gas volume \rightarrow replace foam core under o-rings with FR-4 ... we plan to test this idea with a full-scale prototype





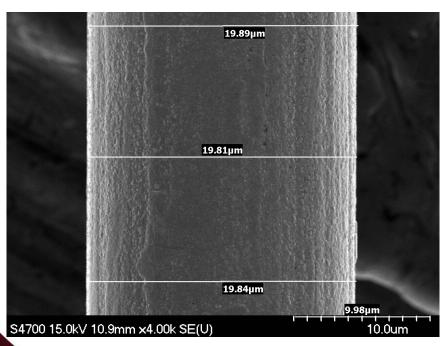
Impact of Modified Frame Design





Wire Quality

- •We have received the full amount of 20 μm W sense wire and 80 μm CuBe field wire for the full assembly
 - •Gold coating looks good under optical microscope
 - •Samples from each spool met the spec for tensile strength



Sample SEM image of sense wire



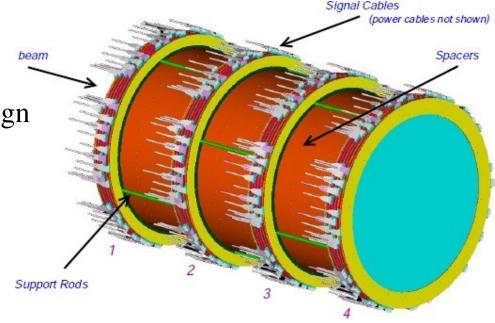
Test plan for full-scale prototype

- •Start out testing 2-layer configuration
 - •Basic mechanical and electrical tests (checking for shorts, etc.)
 - •Wire conditioning
 - •Tests with Sr-90 and Fe-55 sources
 - •HV plateau, obtain operating sense and field HV settings
 - Study responses of wires and strips with different lengths
 - Tests with cosmic rays
 - •Map out performance as function of position (edge effects?)
- Three-layer configuration
 - Readout with 125Mz Flash-ADC



Further prototypes

- •Work is underway to construct a cathode sandwich + new wire frame laminate → include in full scale prototype
- Mechanical prototype planned
 - •Cable packing scheme
 - •Cooling loops
 - •HV distribution attachment
 - •Exoskeleton (inter-package) design
 - Survey points
 - Installation schemes
 - **3**





Steps toward a final product

- •Final design of wire frame PCBs is now underway
- •Planning is underway on final rigid-flex and cathode designs
- •Cathode material has been delivered for production boards
- •Procurement of wire frame PCBs and cathodes will take place in the spring (~April).
- •Procurement of G10 for frames will begin in February.
- •Plan to start production wire winding Oct. 1.
 - Winding will take place at IUCF (same facility as for prototype)
 - IUCF ready to work with us to prepare "Phase 3" contract and come up with budget estimate